

On-Chip Communication Fault-Resilient Adaptive Architectures and Algorithms for 3D-IC Technologies

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Era of Many-core Chips

Hundreds of cores integrated on chip:

- ► Technology scaling.
- ► 3D integration.
- Several examples:
 - ► STMicro P2012/STHORM
 - picoChip
 - Scale-out
 - ► Tilera Tile GX, Tile Pro
- Intel Polari
- Complex apps, stringent constraints:
 - Massively parallel applications
 - Performance, power, scalability, reliability are key challenges.

Router 1 TSV Landing Pad (a) (b) Vertical connection; (c) Router; (d) Wrapped router.

Reliability Demand

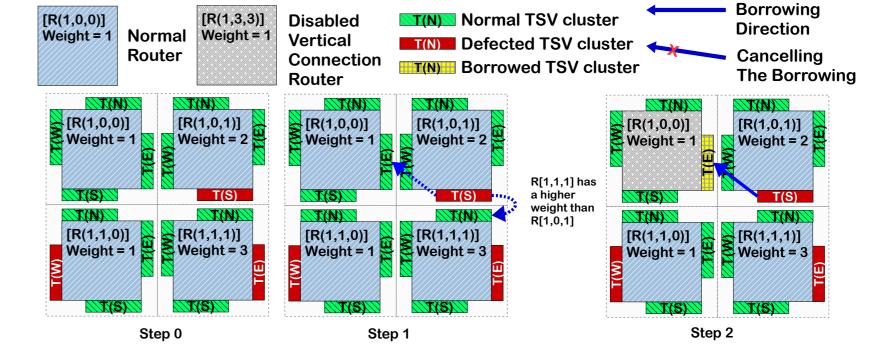
- ► NoCs are exposed to a variety of manufacturing and design factors making them vulnerable to different faults that cause corrupted message transfer or even catastrophic system failures.
- ► The single-point-failure nature of NoC introduces a big concern to their reliability as they are the sole communication medium.
- ➤ Several works have dealt with separated types of faults; however, there is a demand of a comprehensively reliable 3D NoC system which can handle soft errors, hard faults and TSV defects.

Uniform

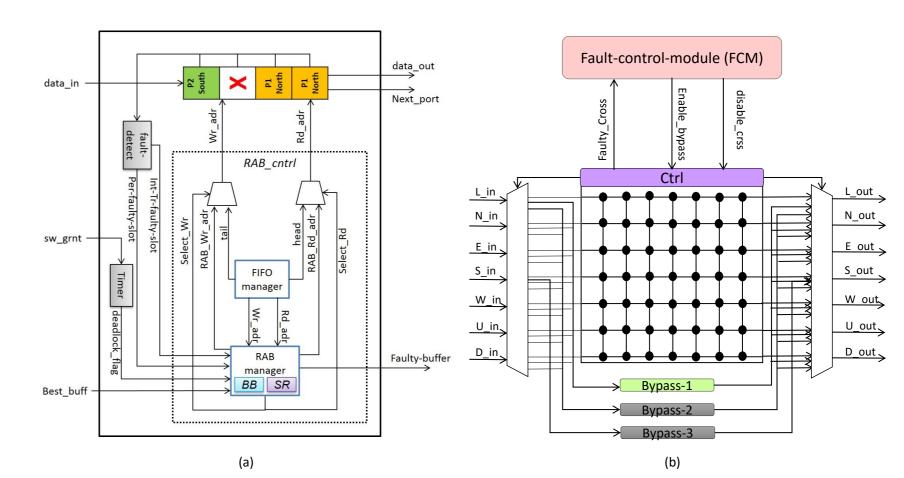
Transpose

Matrix

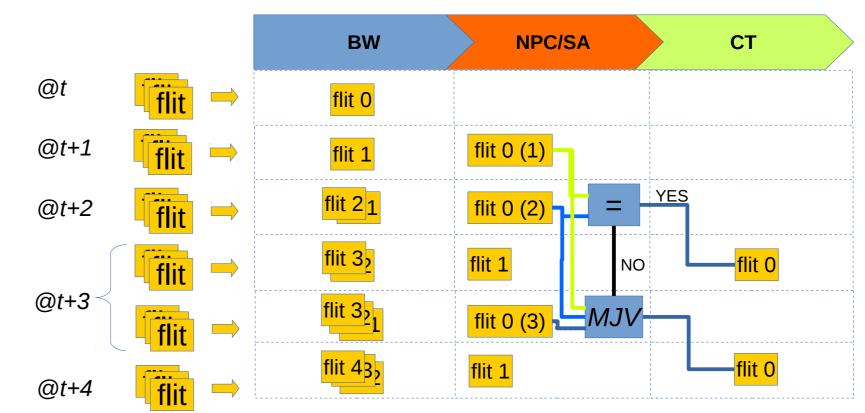
Technology Features



TSV Sharing Process.



Hard Fault Tolerance: (a) Random Access Buffer; (b) Bypass-Link-on-Demand.



Soft Error Tolerance: Pipeline Computation Redundancy.

References

- [1] Dang Nam Khanh: *Development of On-Chip Communication Fault-Resilient Adaptive Architectures and Algorithms for 3D-IC Technologies*, Doctoral Thesis, The University of Aizu, 2017.
- [2] Akram Ben Ahmed: High-throughput Architecture and Routing Algorithms Towards the Design of Reliable Mesh-based Many-Core Network-on-Chip Systems, Doctoral Thesis, The University of Aizu, 2015.

Result: Reliability, Performance and Layout Normal w/o FT — Virtual XXXX Serial Disable I Normal r configuration (%) configuration (%) 50 er ë er Ratio of rout Ratio of rout Ratio of rout 30 30 30 20 10 5.0 10.0 15.0 20.0 25.0 30.0 35.0 40.0 45.0 50.0 5.0 10.0 15.0 20.0 25.0 30.0 35.0 40.0 45.0 50.0 10.0 15.0 20.0 25.0 30.0 35.0 40.0 45.0 50.0 TSV cluster defect rate (%) TSV cluster defect rate (%) TSV cluster defect rate (%) (c) (a) Reliability evaluation. Layer size: (a) 16×16 ; (b) 32×32 ; (c) 64×64 . Baseline 0% 1% [5% 10% E 20% 30% Average Latency (*cycles/packet*) 80 60

PIP

MWD

H.264

Layout of a 2×2 layer.

VOPD

Hotspot

Performance evaluation.